Publications

PUBLICATIONS

• Cooling future system-on-chips with diamond inter-tiers *CELL REPORTS PHYSICAL SCIENCE*
  2023; 4 (12)

• EMBER: A 100 MHz, 0.86 mm<sup>2</sup>, Multiple-Bits-per-Cell RRAM Macro in 40 nm CMOS with Compact Peripherals and 1.0 pJ/bit Read Circuitry
  IEEE.2023: 469-472

• Thermal Scaffolding for Ultra-Dense 3D Integrated Circuits
  IEEE.2023

• Ultra-Dense 3D Physical Design Unlocks New Architectural Design Points with Large Benefits
  IEEE.2023

• Testbench on a Chip: A Yield Test Vehicle for Resistive Memory Devices
  IEEE.2023: 576-582